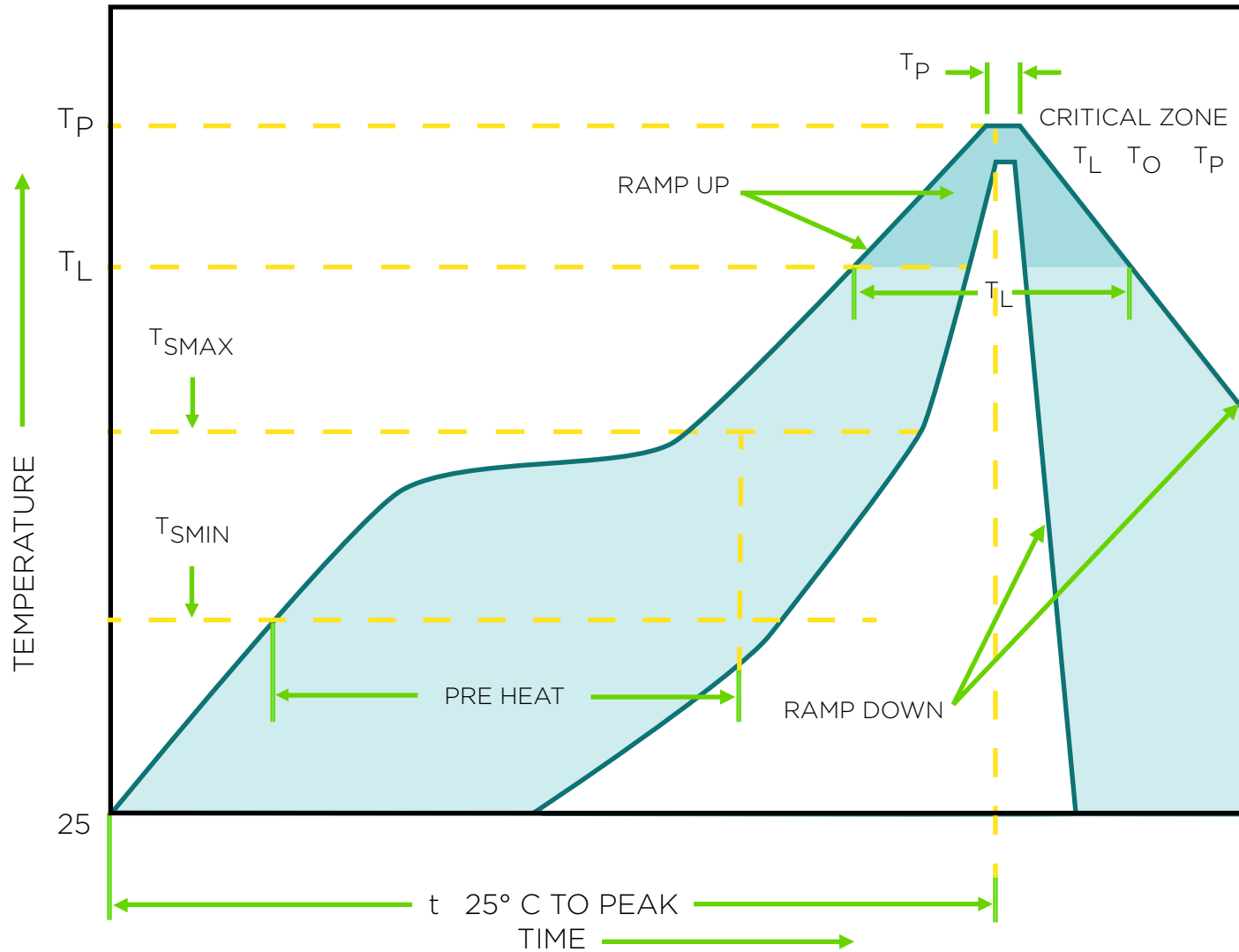


PULSE RECOMMENDED SOLDER REFLOW PROFILE IR/CONVECTION REFLOW PROFILE (IPC/JEDEC J-STD-020C)



PULSE RECOMMENDED SOLDER REFLOW PROFILE

IR/CONVECTION REFLOW PROFILE (IPC/JEDEC J-STD-020C)

Table 1: Lead-free reflow profile recommendation (reference IPC/JEDEC J-STD-020C).

NOTE: All of the Pulse SMT power parts are tested using a reflow profile similar to that outlined in the JEDEC-STD-020 specification and are capable of handling up to 260C peak reflow for 5-10seconds.

Reflow Parameter

Minimum preheat temperature (Ts MN)
 Maximum preheat temperature (Ts Max)
 Preheat time
 Ts Max to Tl ramp-up rate
 Time above temperature Tl (tl)
 Peak temperature (Tp)
 Time 25 degrees C to Tp
 Time within 5 degrees C of peak Tp
 Ramp-down rate

Lead-Free Assembly

150 degrees C
 200 degrees C
 60 to 180 seconds
 3 degrees C per second maximum
 217 degrees C for 60 to 150 seconds
 245-260 degrees C
 8 minutes maximum
 20 to 40 seconds
 6 degrees C per seconds maximum

Notes for Table 1: Note 1 – All temperatures measured on the package leads.

Note 2 – Attach a thermocouple to the component body surface during profiling to determine difference between body and lead temperature for reference only.

Table 2: Lead-free process peak reflow temperatures. (Temperature tolerance = +0, -5 degrees C).

NOTE: To be used for MSL Classification ONLY

Package thickness

<1.60mm
 1.60mm to 2.50mm
 >2.50mm

Volume mm³ < 350

260 degrees C
 260 degrees C
 250 degrees C

Volume mm³ = 350 to 2000

260 degrees C
 250 degrees C
 245 degrees C

Volume mm³ > 2000

260 degrees C
 245 degrees C
 245 degrees C